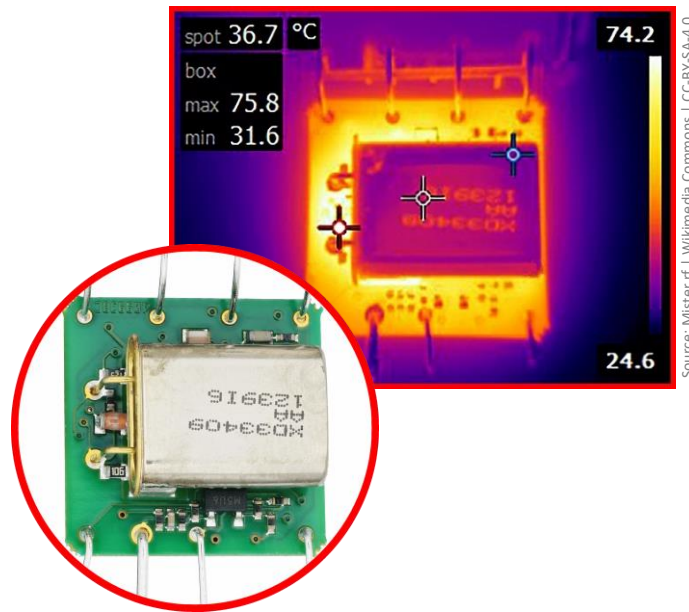


SEC TECH-CLASS

March 12 to 14, 2024



THE ESSENTIALS OF THERMAL FOR ELECTRONICS



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DETAILS

- From Tuesday March 12, 2024 at 8:30 a.m.
- Until Thursday March 14, 2024 at 12:00 p.m.
- Location: [Ateliers Industriels CFF, Quai des Ateliers 1, 1400 YVERDON-LES-BAINS](#)
- Minimum number of registrations: 05
- Maximum number of registrations: 12
- Language: French
- Registration closure: February 25, 2024

EDUCATIONAL GOALS

- Acquire precise knowledge of the physical phenomena involved in heat transfer within electronic devices
- Know the different technical heat removal processes in these devices and know how to choose them
- Know how to correctly size the thermal process(es) implemented in the designs of electronic or electrical equipment through simulation

TARGET AUDIENCE

- Electronic and mechanical technicians and engineers

PREREQUISITE

- Mathematics basics baccalaureate level, use of a spreadsheet
- Some theoretical notions require a mathematical level of second year university to be fully assimilated
- General knowledge of electronics, no initial thermal knowledge is necessary



REGISTRATION FEES

- Non-member of the **SEC**: CHF 2'000.- / person
- **SEC BLUE** member: CHF 1'000.- / person
- **SEC SILVER** or **SEC GOLD** member: CHF 500.- / person
- **SEC SPONSOR** member: Free
- Payment term: in advance

TRAINER

- Philippe GUILLEMET, Director of Thermodel-rd, thermal expert in a design office specializing in electronics, former teacher-researcher at the University of Nantes

DESCRIPTION

- 1. Modes of heat transfer**
 - Transfer by conduction
 - Transfer by convection
 - Transfer by radiation
- 2. Heat removal devices**
 - Thermal of interfaces, films and pastes
 - Conventional cooling methods
 - Sophisticated cooling methods
 - Critical and comparative analysis of methods, tips for use, pitfalls to avoid
- 3. Thermal of the PCB**
 - Thermal of tracks on PCB
 - Thermal of components on PCB
- 4. Methods for calculating and simulating heat transfers**
 - Thermal sizing method
 - Thermal analysis of a device and simplification
 - Elementary analytical calculation of sizing
 - Critical analysis of the result and the search for optimization
 - Application exercises
 - Simulation methodology
- 5. Measurement of thermal and fluid quantities**
 - Temperature measurement
 - Other thermophysical measurements
- 6. Forms and digital data**
 - Calculation tools
 - Data tables
- 7. Practical case studies**
 - Free discussion around the different situations proposed by the trainees

ONLINE REGISTRATION

By following [THIS LINK](#)

Or by scanning the QR-code:



The **SEC** is an initiative of [CapQua Sàrl](#), the [FSRM](#) and the [GESO](#) supported by the canton of Neuchâtel and the SECO under the NPR.